

Application No. P04870US1

**AMENDMENT — VERSION WITH MARKINGS
TO SHOW CHANGES MADE**

In the Title

Please amend the title to:

METHOD FOR MANUFACTURING A POWER CHIP RESISTOR

In The Specification

Please add the following as the first paragraph of the Specification:

PRIORITY STATEMENT

This application is a Divisional of U. S. Patent Application Serial No. 09/811,844 filed on
March 19, 2001.

In The Abstract

~~A method and apparatus for a stacked power chip is disclosed. The invention provides for multiple power chip resistors to be stacked, providing for encapsulant such as glass to separate each power chip resistor and a metal barrier such as nickel plating on each end of the stacked power chip resistor to provide for electrical and mechanical connection of each power chip resistor in the stack.~~

The invention provides for a method of manufacturing a stacked power chip resistor. The method includes adhering a first chip resistor to a second chip resistor with a glass encapsulant, connecting a first terminal of the first chip resistor to a first terminal of the second chip resistor